



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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### Features

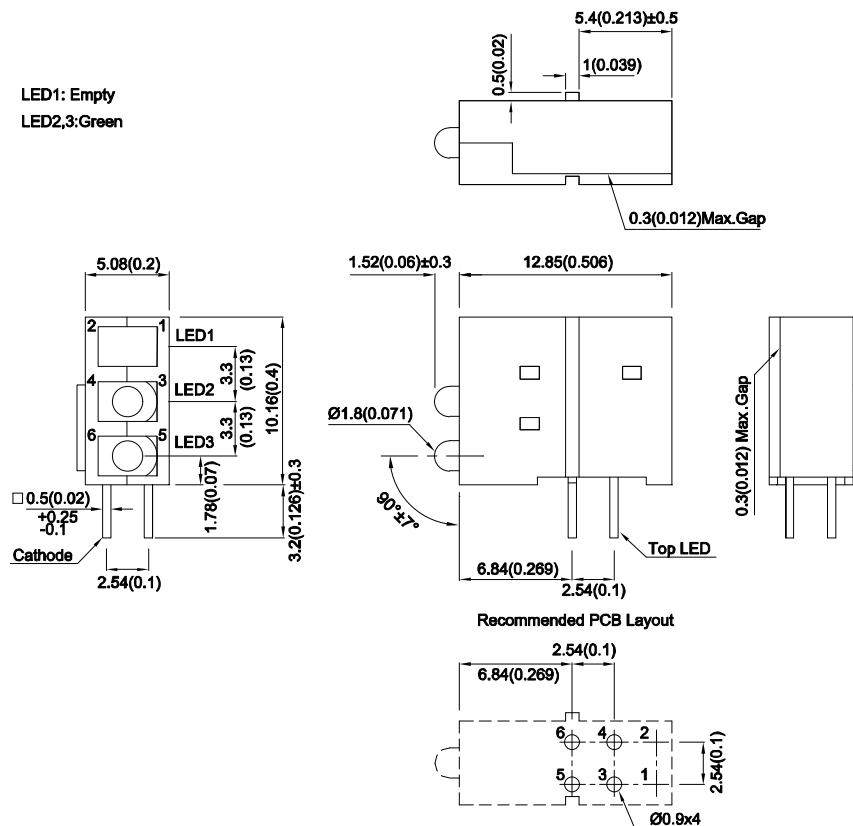
- Pre-trimmed leads for pc mounting
- Black case enhances contrast ratio
- High reliability life measured in years
- Housing UL rating: 94V-0
- Housing material: type 66 nylon
- RoHS compliant

### Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

### Package Dimensions

LED1: Empty  
LED2,3: Green



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the lead emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



## Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Iv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP406A10XHA/X2GD	Green (GaP)	Green Diffused	6	12	70°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous Flux: +/-15%.
3. Luminous intensity value is traceable to CIE127-2007 standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Green	565		nm	I <sub>F</sub> =10mA
λ <sub>D</sub> [1]	Dominant Wavelength	Green	568		nm	I <sub>F</sub> =10mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Green	30		nm	I <sub>F</sub> =10mA
C	Capacitance	Green	15		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	Green	2	2.5	V	I <sub>F</sub> =10mA
I <sub>R</sub>	Reverse Current	Green		10	uA	V <sub>R</sub> = 5V

Notes:

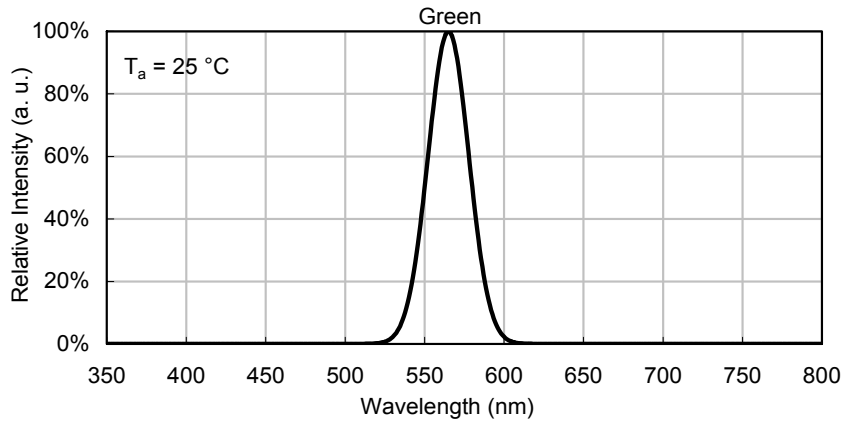
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

## Absolute Maximum Ratings at TA=25°C

Parameter	Values	Units
Power dissipation	62.5	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

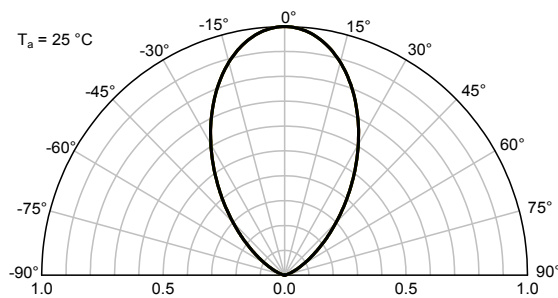
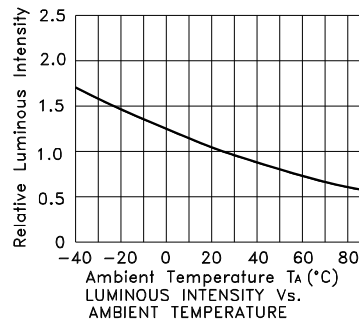
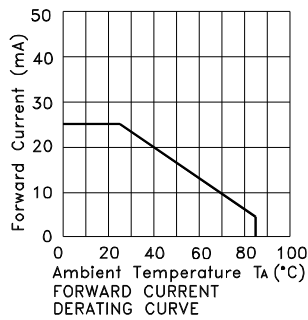
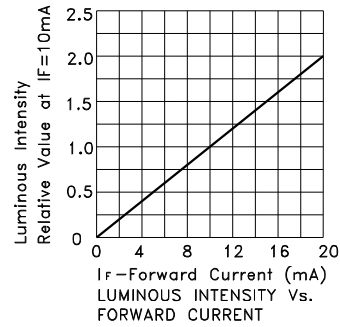
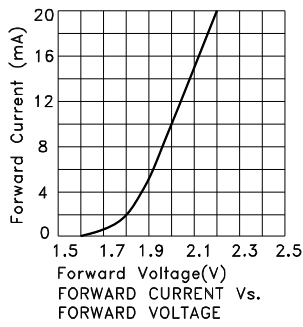
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.
4. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



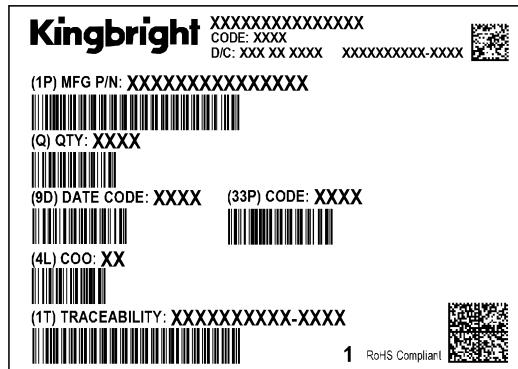
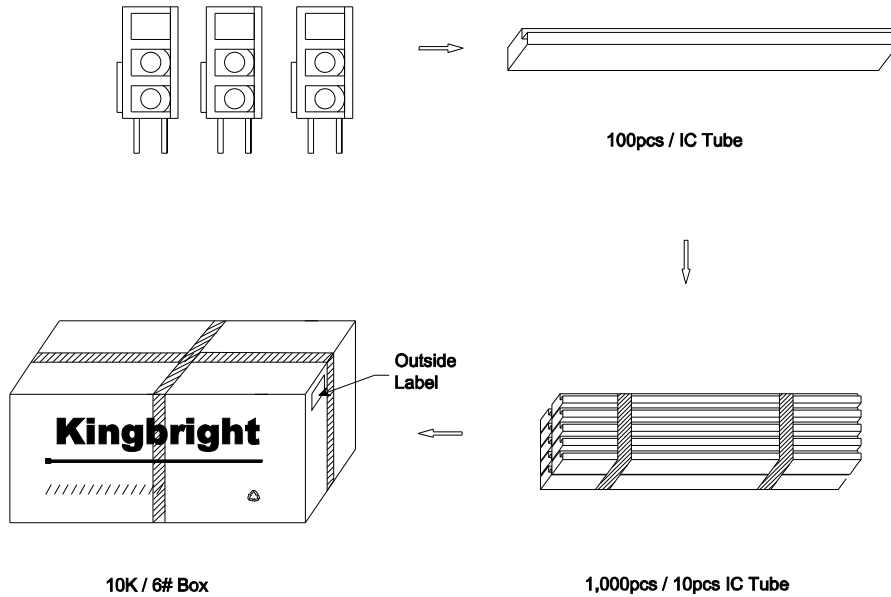
Green

WP406A10XHA/X2GD



## PACKING & LABEL SPECIFICATIONS

## WP406A10XHA/X2GD



### Terms and conditions for the usage of this document

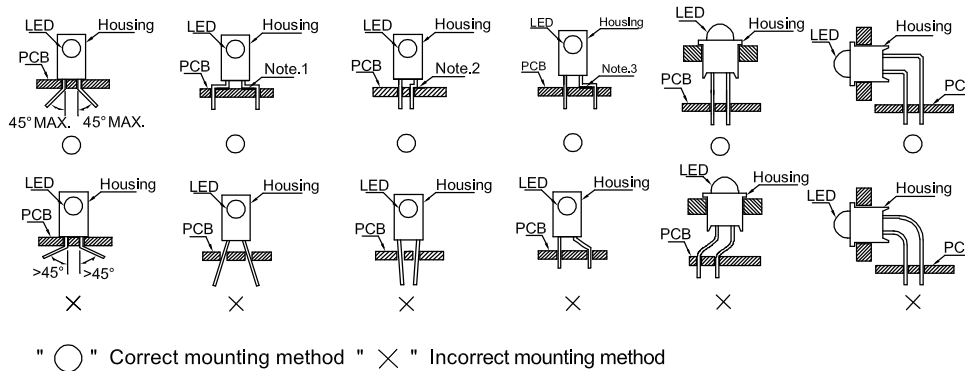
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## PRECAUTIONS

### 1. Storage conditions:

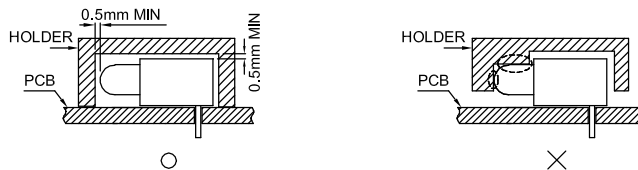
- a. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- b. LEDs should be stored with temperature  $\leq 30^{\circ}\text{C}$  and relative humidity  $< 60\%$ .
- c. Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at  $85 \sim 100^{\circ}\text{C}$ .

### 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

### 3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.

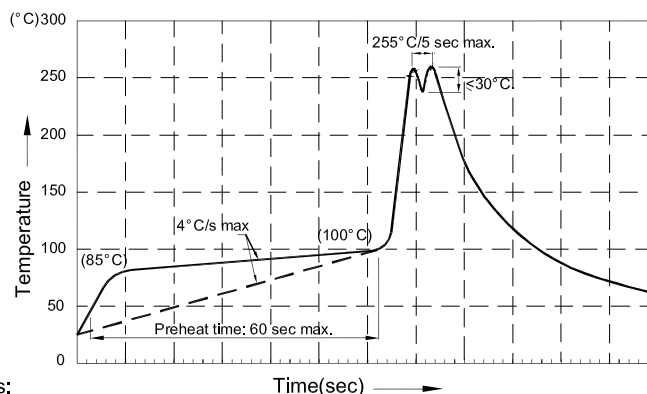


### 4. The tip of the soldering iron should never touch the lens epoxy.

### 5. Through-hole LEDs are incompatible with reflow soldering.

### 6. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

### 7. Recommended Wave Soldering Profiles:



Notes:

1. Recommend pre-heat temperature of  $105^{\circ}\text{C}$  or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of  $260^{\circ}\text{C}$
2. Peak wave soldering temperature between  $245^{\circ}\text{C} \sim 255^{\circ}\text{C}$  for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above  $85^{\circ}\text{C}$ .
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.